Title (en)

Method of coating metal substrates with a powder primer and a surface coat applied by dipping and product obtained

Title (de)

Verfahren zur Beschichtung eines Metallsubstrats mit Pulvergrundierungsschicht und mittels Tauchen angebrachte Oberflächenbeschichtung und so erhaltene Materialien

Title (fr)

Procédé pour revêtir des substrats métalliques à l'aide d'un primaire en poudre et d'un revêtement superficiel appliqué par trempage et matériaux composites obtenus

Publication

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Application

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Priority

FR 8814332 A 19881103

Abstract (en)

[origin: EP0367653A1] The present invention relates to the field of coatings of metal substrates applied by dipping. It relates to a method of coating a metal substrate using a surface coat applied by dipping after coating of said substrate with a powder primer. It also relates to powder compositions which can be used as adhesion primer, as well as to composite materials: metal substrates/adhesion primer/surface coat.

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IPC 8 full level

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CPC (source: EP US)

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